

EMC IC modelling - Part 3: Models of Integrated Circuits
for EMI behavioural simulation - Radiated emissions
modelling (ICEM-RE)

EESTI STANDARDI EESSÕNA

NATIONAL FOREWORD

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ICS 31.200, 33.100.10

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ICS 33.100.10; 31.200

English Version

EMC IC modelling - Part 3: Models of Integrated Circuits for EMI
behavioural simulation - Radiated emissions modelling (ICEM-
RE)
(IEC 62433-3:2017)

Modèles de circuits intégrés pour la CEM - Partie 3:
Modèles de circuits intégrés pour la simulation du
comportement lors de perturbations électromagnétiques -
Modélisation des émissions rayonnées (ICEM-RE)
(IEC 62433-3:2017)

EMV-IC-Modellierung - Teil 3: Modelle integrierter
Schaltungen für die Simulation des Verhaltens bei
elektromagnetischer Beeinflussung - Modellierung von
abgestrahlten Aussendungen (ICEM-RE)
(IEC 62433-3:2017)

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Comité Européen de Normalisation Electrotechnique
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European foreword

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The following dates are fixed:

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standard or by endorsement
- latest date by which the national (dow) 2020-03-03
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document have to be withdrawn

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In the official version, for Bibliography, the following note has to be added for the standard indicated:

ISO 8879:1986

NOTE Harmonized as EN 28879:1990¹⁾

1) Withdrawn publication

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

| <u>Publication</u> | <u>Year</u> | <u>Title</u> | <u>EN/HD</u> | <u>Year</u> |
|---------------------|-------------|---|---------------|-------------|
| IEC 61967-1 | - | Integrated circuits - Measurement of electromagnetic emissions, 150 kHz to 1 GHz -- Part 1: General conditions and definitions | EN 61967-1 | - |
| IEC 62433-2 | - | EMC IC modelling - Part 2: Models of integrated circuits for EMI behavioural simulation - Conducted emissions modelling (ICEM-CE) | FprEN 62433-2 | - |
| IEC/TS 61967-3 | - | Integrated circuits - Measurement of electromagnetic emissions - Part 3: Measurement of radiated emissions - Surface scan method | - | - |
| IEC/TS 62433-1:2011 | - | EMC IC modelling - Part 1: General modelling framework | - | - |
| ANSI INCITS 4 | - | Information Systems - Coded Character Sets - 7-Bit American National Standard Code for Information Interchange (7-Bit ASCII) | - | - |

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